Product Change Notification

Change Notification #: 115589 - 00

Change Title: Select Intel® Optane™ Memory Series Products, PCN 115589-00, Label, Caution and Regulatory Label Update

Date of Publication: June 15, 2017

Key Characteristics of the Change:

Label

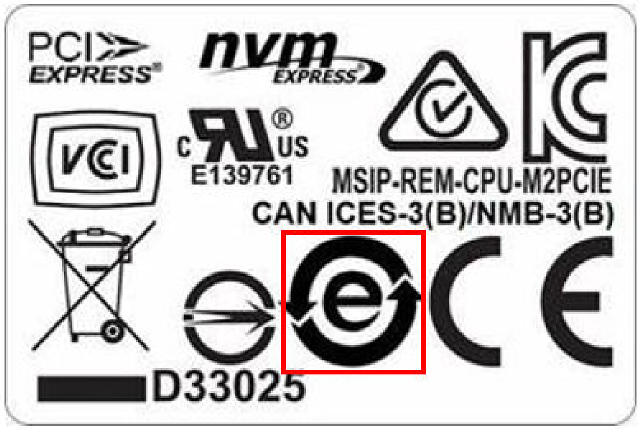
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	June 15, 2017

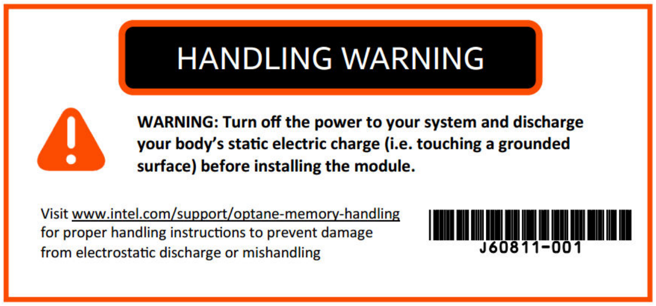
Description of Change to the Customer:

Intel Corporation will be making the following label changes to the Intel® Optane™ Memory Series SKUs listed in the "Products Affected/Intel Ordering Codes" table below:

1. Replace Bottom Custom Label (Regulatory Label)

Current label:	New label:
	

2. Add Handling Warning to flyer:



HANDLING WARNING

WARNING: Turn off the power to your system and discharge your body's static electric charge (i.e. touching a grounded surface) before installing the module.

Visit www.intel.com/support/optane-memory-handling for proper handling instructions to prevent damage from electrostatic discharge or mishandling

J60811-001

3. Replace current Material Declaration Data Sheet (MDDS) with new Circle-E RoHS MDDS:

Current China RoHS MDDS

Material Declaration Data Sheet

New China RoHS MDDS

China RoHS Declaration

产品中有毒有害物质的名称及含量

Hazardous Substances Table

部件名称 Component Name	有毒有害物质或元素 Hazardous Substance					
	铅 Pb	汞 Hg	镉 Cd	六价铬 Cr (VI)	多溴联苯 PBB	多溴二苯醚 PBDE
固态硬盘 Solid State Drive	○	○	○	○	○	○

○：表示该有毒有害物质在该部件所有均质材料中的含量均在 GB/T 26572 标准规定的限量要求以下。

○：Indicates that this hazardous substance contained in all homogeneous materials of such component is within the limits specified in GB/T 26572.

×：表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 GB/T 26572 标准规定的限量要求。

×：Indicates that the content of such hazardous substance in at least a homogeneous material of such component exceeds the limits specified in GB/T 26572.

对销售之日的所售产品，本表显示我公司供应链的电子信息产品可能包含这些物质。注意：在所售产品中可能会也可能不会含有所有所列的部件。

This table shows where these substances may be found in the supply chain of our electronic information products, as of the date of sale of the enclosed product. Note that some of the component types listed above may or may not be a part of the enclosed product.

除非另外特别的标注，此标志为针对所涉及产品的环保使用期限标志. 某些可更换的零部件可能会有一个不同的环保使用期限(例如，电池单元模块). 此环保使用期限只适用于产品在产品手册中所规定的条件下工作.

The Environment-Friendly Use Period (EFUP) for all enclosed products and their parts are per the symbol shown here, unless otherwise marked. Certain field-replaceable parts may have a different EFUP (for example, battery modules) number. The Environment-Friendly Use Period is valid only when the product is operated under the conditions defined in the product manual.

J53291-001

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. The change is only to the labels used in packaging.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Post Change TA
Intel® Optane™ Memory Series (16GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Generic Single Pack	MEMPEK1W016GA01	953340	J45694-100	J45694-101
Intel® Optane™ Memory Series (32GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Generic Single Pack	MEMPEK1W032GA01	953341	J45695-100	J45695-101
Intel® Optane™ Memory Series (16GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Retail Box 10pk	MEMPEK1W016GAXT	957790	J57060-100	J57060-101
Intel® Optane™ Memory Series (32GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Retail Box 10pk	MEMPEK1W032GAXT	957793	J57061-100	J57061-101
Intel® Optane™ Memory Series (16GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Generic 100pk	MEMPEK1W016GA	957794	J57062-100	J57062-101
Intel® Optane™ Memory Series (16GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Generic 100pk	MEMPEK1W032GA	957795	J57063-100	J57063-101

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
June 15, 2017	00	Originally Published PCN

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115589 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Europe Email: eccb@intel.com
Japan Email: jccb.ijkk@intel.com

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